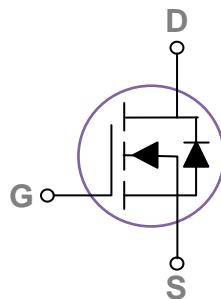
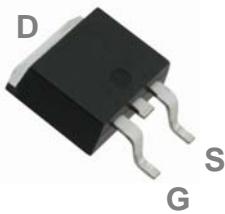


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO252 Pin Configuration



BVDSS	RDS(ON)	ID
20V	25mΩ	20A

### Features

- 20V, 20A, RDS(ON) = 25mΩ@VGS = 4.5V
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for 1.8V Gate Drive Applications

### Applications

- Notebook
- Load Switch
- Hand-Held Instruments
- Networking

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 10$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	20	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	12	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	80	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	20.8	W
	Power Dissipation – Derate above 25°C	0.167	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	6	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	20	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.02	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=16\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=16\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=85^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 10\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=4.5\text{V}$ , $I_D=4\text{A}$	---	21	25	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$ , $I_D=3\text{A}$	---	28	36	
		$V_{\text{GS}}=1.8\text{V}$ , $I_D=2\text{A}$	---	39	51	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	0.4	0.6	1	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-2	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_S=3\text{A}$	---	7	---	S

**Dynamic and switching Characteristics**

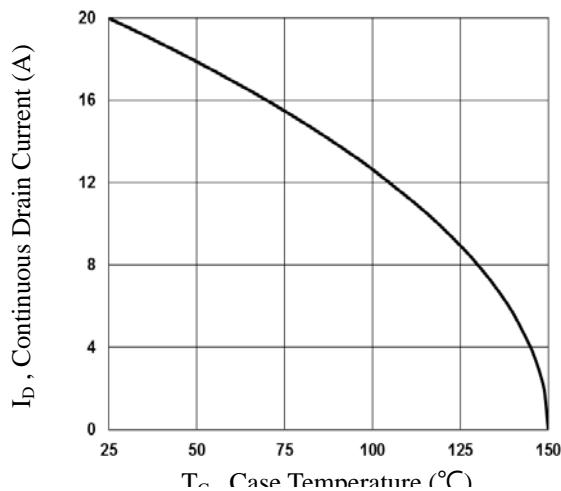
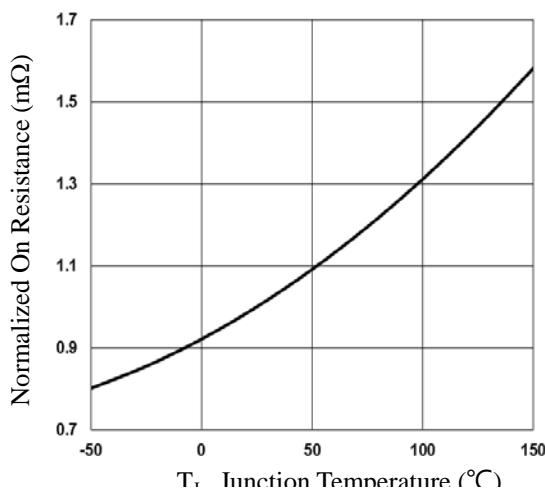
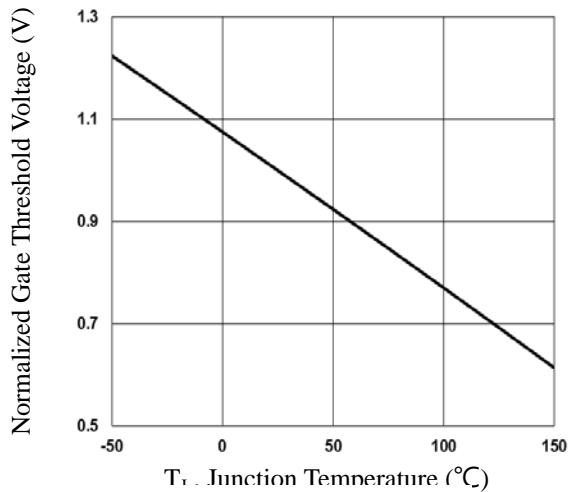
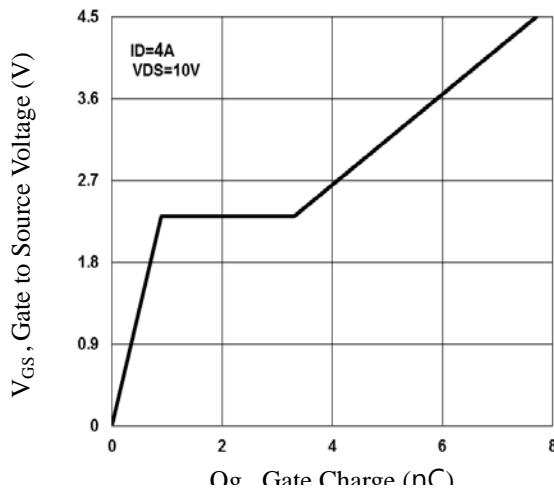
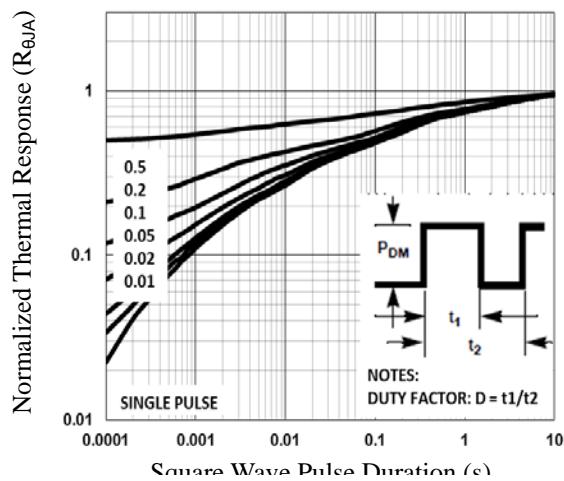
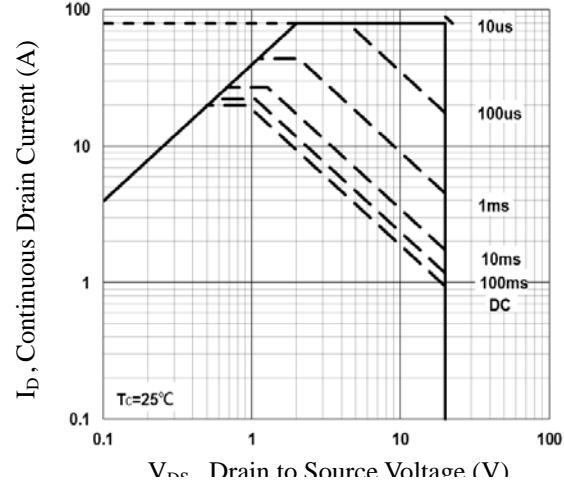
$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{\text{DS}}=10\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=4\text{A}$	---	7.7	11	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2,3</sup>		---	0.9	1	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2,3</sup>		---	2.4	5	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2,3</sup>	$V_{\text{DD}}=10\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $R_G=25\Omega$ $I_D=1\text{A}$	---	4.1	8	nS
$T_r$	Rise Time <sup>2,3</sup>		---	11.6	22	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2,3</sup>		---	23.9	45	
$T_f$	Fall Time <sup>2,3</sup>		---	7.6	14	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=10\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	535	775	pF
$C_{\text{oss}}$	Output Capacitance		---	60	85	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	34	50	

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	20	A
$I_{\text{SM}}$	Pulsed Source Current		---	---	40	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.


**Fig.1** Continuous Drain Current vs.  $T_C$ 

**Fig.2** Normalized  $R_{DS(on)}$  vs.  $T_J$ 

**Fig.3** Normalized  $V_{th}$  vs.  $T_J$ 

**Fig.4** Gate Charge Waveform

**Fig.5** Normalized Transient Impedance

**Fig.6** Maximum Safe Operation Area

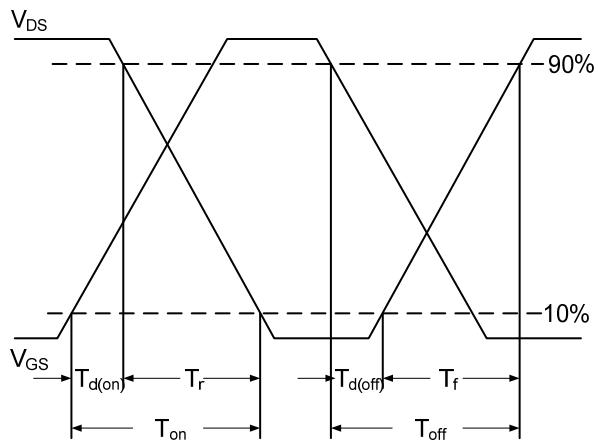


Fig.7 Switching Time Waveform

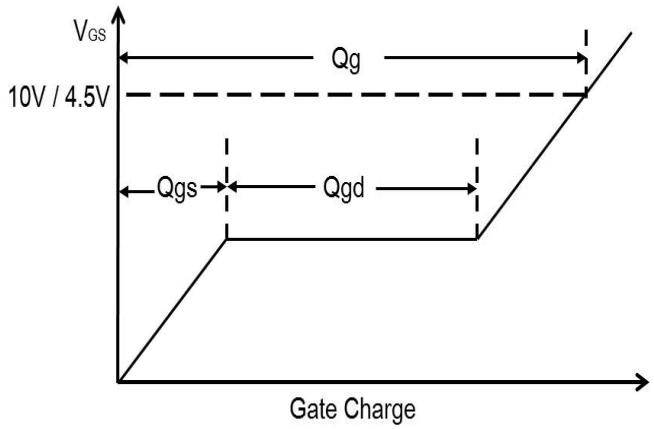
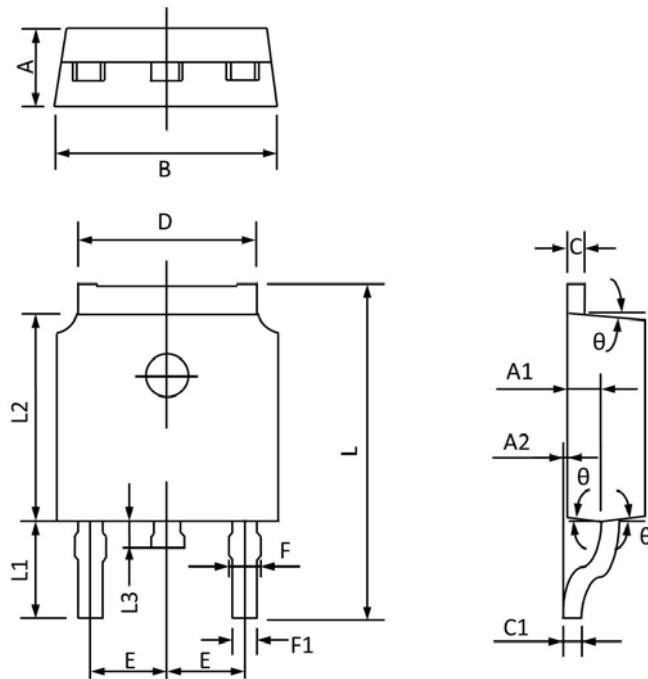


Fig.8 Gate Charge Waveform

## TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.20	2.40	0.087	0.094
A1	0.91	1.11	0.036	0.044
A2	0.00	0.15	0.000	0.006
B	6.50	6.70	0.256	0.264
C	0.46	0.580	0.018	0.230
C1	0.46	0.580	0.018	0.030
D	5.10	5.46	0.201	0.215
E	2.186	2.386	0.086	0.094
F	0.74	0.94	0.029	0.037
F1	0.660	0.860	0.026	0.034
L	9.80	10.40	0.386	0.409
L1	2.9REF		0.114REF	
L2	6.00	6.20	0.236	0.244
L3	0.60	1.00	0.024	0.039
θ	3°	9°	3°	9°